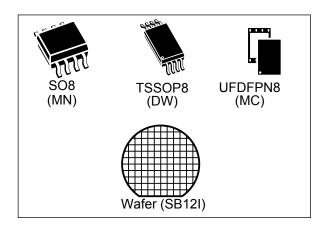


M24SR64-Y

Data brief

Dynamic NFC/RFID tag IC with 64-Kbit EEPROM, NFC Forum Type 4 Tag and I²C interface



Features

I²C interface

- Two-wire I²C serial interface supports 1 MHz protocol
- Single supply voltage: 2.7 V to 5.5 V

Contactless interface

- NFC Forum Type 4 Tag
- ISO/IEC 14443 Type A
- 106 Kbps data rate
- Internal tuning capacitance: 25 pF

Memory

- 8-Kbyte (64-kbit) EEPROM
- Support of NDEF data structure
- Data retention: 200 years
- Endurance: 1 million erase-write cycles
- Read up to 246 bytes in a single command
- Write up to 246 bytes in a single command
- 7 bytes unique identifier (UID)
- 128 bits passwords protection

Package

- 8-lead small-outline package (SO8) ECOPACK[®]2
- TSSOP8 ECOPACK[®]2
- UFDFPN8 ECOPACK[®]2

Digital pad

- GPO: configurable General Purpose Output
- RF disable: activation/deactivation of RF commands

Description

The M24SR64-Y device is a dynamic NFC/RFID tag IC with a dual interface. It embeds an EEPROM memory. It can be operated from an I^2C interface or by a 13.56 MHz RFID reader or an NFC phone.

The I^2C interface uses a two-wire serial interface, consisting of a bidirectional data line and a clock line. It behaves as a slave in the I^2C protocol.

The RF protocol is compatible with ISO/IEC 14443 Type A and NFC Forum Type 4 Tag.

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1 Functional description

The M24SR64-Y device is a dynamic NFC/RFID tag that can be accessed either from the I^2C or the RF interface. The RF and I^2C host can read or write to the same memory, that is why only one host can communicate at a time with the M24SR64-Y. The management of the interface selection is controlled by the M24SR64-Y device itself.

The RF interface is based on the ISO/IEC 14443 Type A standard. The M24SR64-Y is compatible with the NFC Forum Type 4 Tag specifications and supports all corresponding commands.

The I²C interface uses a two-wire serial interface consisting of a bidirectional data line and a clock line. The devices carry a built-in 4-bit device type identifier code in accordance with the I²C bus definition.

The device behaves as a slave in the I²C protocol.

Figure 1 displays the block diagram of the M24SR64-Y device.

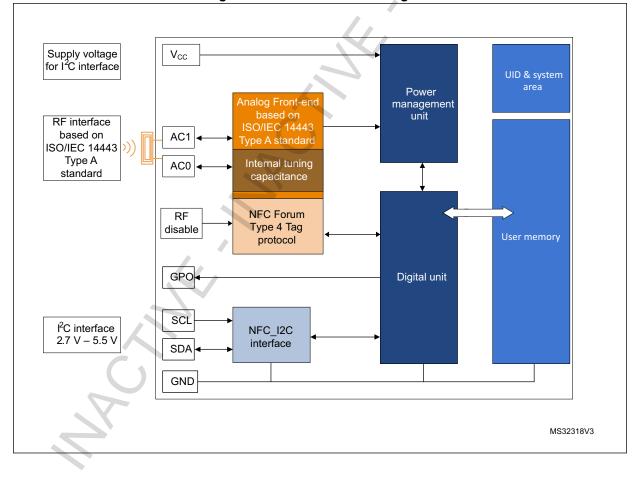


Figure 1. M24SR64-Y block diagram



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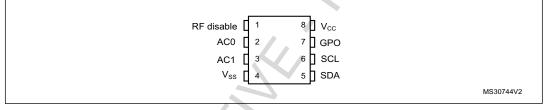
Signal name	Function	Direction	
SDA	Serial data	I/O	
SCL	Serial clock	Input	
AC0, AC1	Antenna coils	-	
V _{CC}	Supply voltage	-	
VSS	Ground	-	
GPO	Interrupt output ⁽¹⁾	Open drain output	
RF disable	Disable the RF communication ⁽²⁾	Input	

Table 1. Signal names

1. An external pull-up > 4.7 k Ω is required.

2. An external pull-down is required when the voltage on V_{cc} is above its POR level.

Figure 2	2. 8-pin	package	connections



1. See Package mechanical data section for package dimensions, and how to identify pin 1.

1.1 Functional modes

The M24SR64-Y has two functional modes available. The difference between the modes lies in the power supply source (see *Table 2*).

Table 2. Functional modes

Modes	Supply source	Comments
I ² C mode	V _{cc}	The I ² C interface is available
Tag mode	RF field only	The I ² C interface is disconnected
Dual interface mode	RF field or V_{cc}	Both I ² C and RF interfaces are available

1.1.1 I²C mode

M24SR64-Y is powered by V_{CC}. The I²C interface is connected to the M24SR64-Y. The I²C host can communicate with the M24SR64-Y device.

1.1.2 Tag mode

The M24SR64-Y is supplied by the RF field and can communicate with an RF host (RFID reader or an NFC phone). The User memory can only be accessed by the RF commands.

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1.1.3 Dual interface mode

Both interfaces, RF and I²C, are connected to the M24SR64-Y and both RF or I²C host can communicate with the M24SR64-Y device. The power supply and the access management are carried out by the M24SR64-Y itself. For further details, please refer to the token mechanism chapter.



2 Part numbering

M24 SR 64-Y /2 Example: MN 6 **Device type** M24 = I^2C interface device **Device feature** SR = Short range Memory size 64 = memory size in Kbits Voltage range Y = 2.7 to 5.5 V Package MN = SO8N DW = TSSOP8 MC = UFDFPN8 SB12I = 120 µm ± 15 µm bumped and sawn inkless wafer on 8-inch frame **Device grade** 6 = industrial: device tested with standard test flow over -40 to 85 °C (No parameter for SB12I) Option T = Tape and reel packing (No parameter for SB12I) Capacitance

Table 3. Ordering information scheme for packaged devices

/2 = 25 pF



3 Revision history

Date	Revision	Changes
14-May-2012	1	Initial release.
14-Jan-2013	2	Reshaped from M24SR64-Y Datasheet, with file sharing; changed different information.
		Updated from M24SR64-Y Datasheet, version 6, including the title change to <i>Dynamic NFC/RFID Tag IC with 4-Kbit EEPROM, NFC Forum Type 4 Tag and I²C interface.</i>
17-Sep-2013	3	Changed the capacitance from 27.5 pF to 23.5 pF in the <i>Features</i> , in <i>Figure 1: M24SR64-Y block diagram</i> and <i>Table 3: Ordering information scheme for packaged devices</i> .
		Added footnote (2) to Table 1: Signal names.
05-Feb-2014	4	Updated from M24SR64-Y Datasheet, version 8. Removed Section 2 : Signal descriptions. Removed Section 3 : M24SR64-Y memory management. Removed Section 4 : Package mechanical data.

Table 4. Document revision history

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